

Notes:

1. No tracks or vias in the shaded "KEEP OUT" AREA.
2. No other track or signal within 0.020" of any contact pad.
3. Do not allow solder paste on the contact pads. It is essential to eliminate any hole in the solder paste-mask (solder stencil) layer. If this is not possible make the contact pads thru-hole with finished hole size of 0.008" or less.
4. To avoid ordering confusion, please specify DNL in your BOM.

FOOTPRINT FOR TC2050-IDC-430 PLUG OF NAILS(TM) CABLE FOR MSP430

REV

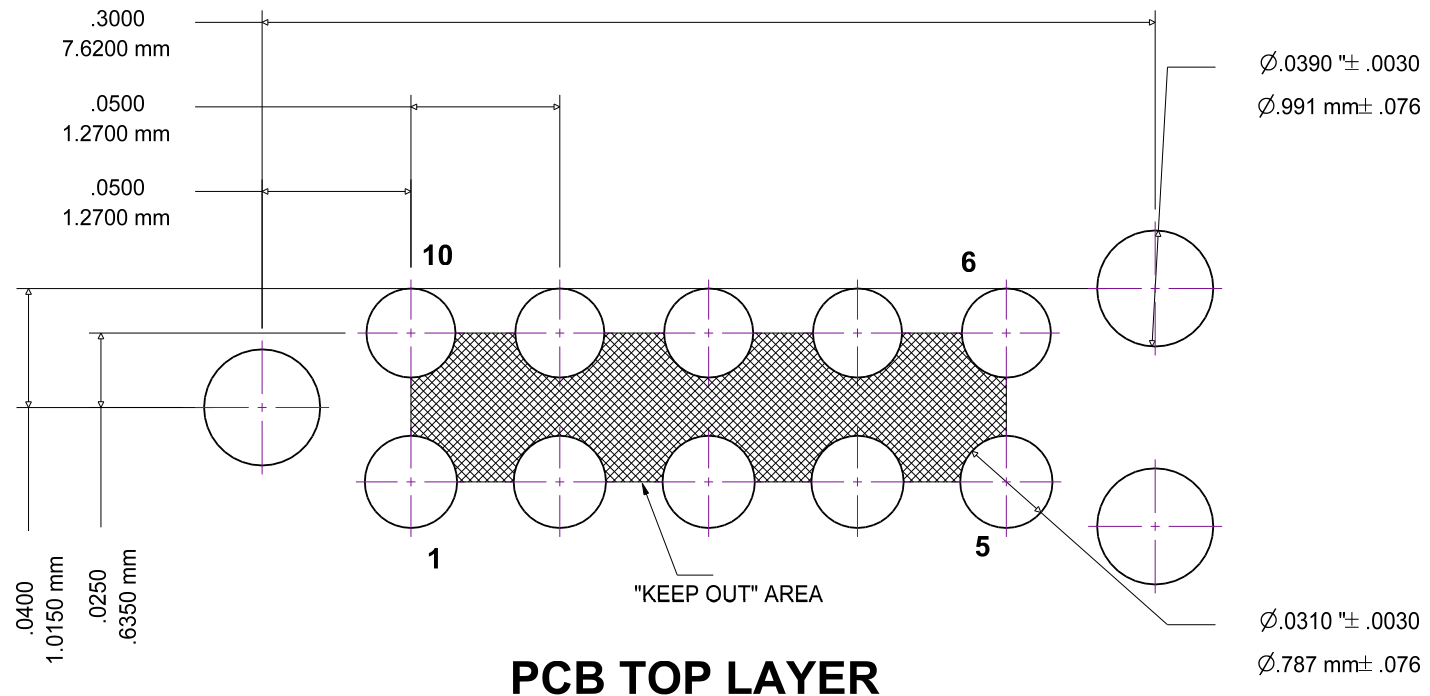
TC2050-IDC-430-FP

11/29/10

MS

5. The TC2050-CLIP board can attach to the three alignment pins from underneath the PCB to temporarily retain the cable in place.

14-pin Ribbon Pin #	TC2050-IDC-430 Pin #
1	1
2	2
...	...
8	8
9	9
10	(NC)
11	10
12	(NC)
13	(NC)
14	(NC)



SIZE A	FSCM NO.	DWG NO.	FOOTPRINT FOR TC2050-IDC-430-FP	REV A
SCALE 10:1	www.TAG-CONNECT.com	SHEET 1 of 3		

TC2050-IDC-430-NL PLUG-OFF-NAILS™ CABLE FOR MSP430

ZONE

REV

TC2050-IDC-430-NL

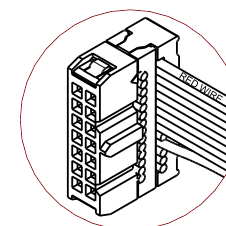
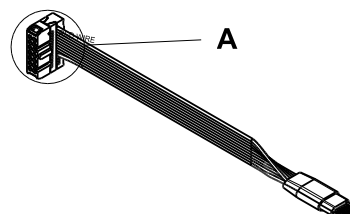
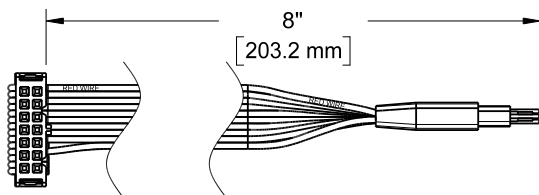
11/29/10

MS

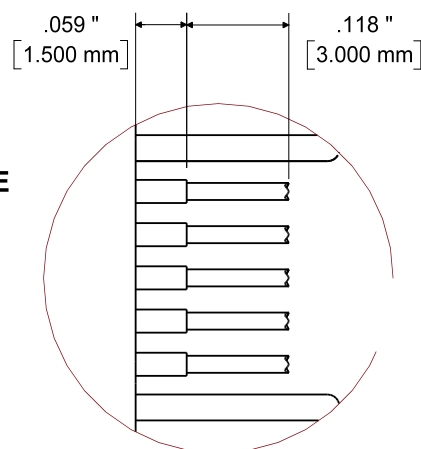
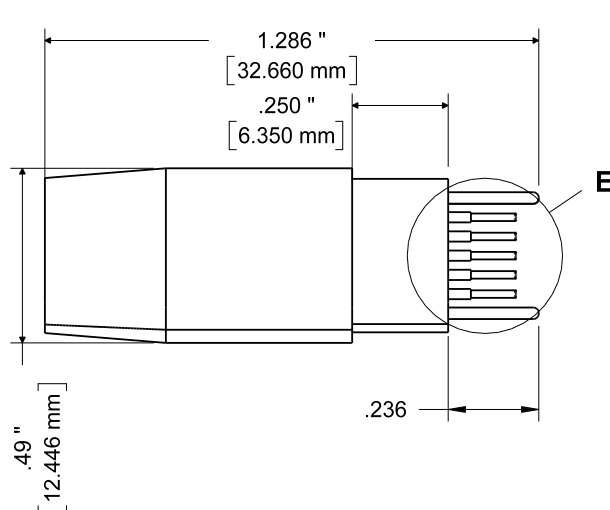
NOTE:

Dimensions subject to change

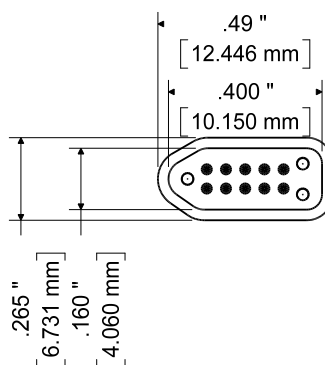
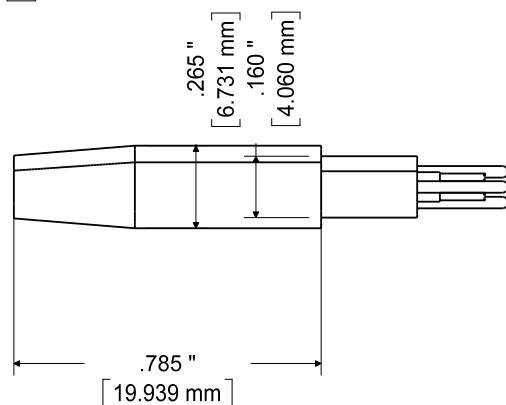
For use with TI MSP-FET and compatible MSP430 JTAG debugger



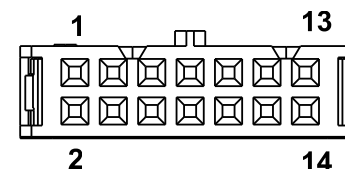
Detail A



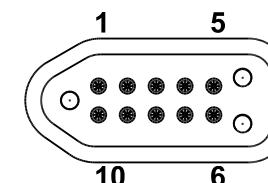
Detail E



END VIEW
2x7 .1" IDC CONNECTOR



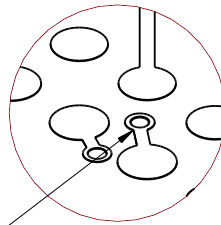
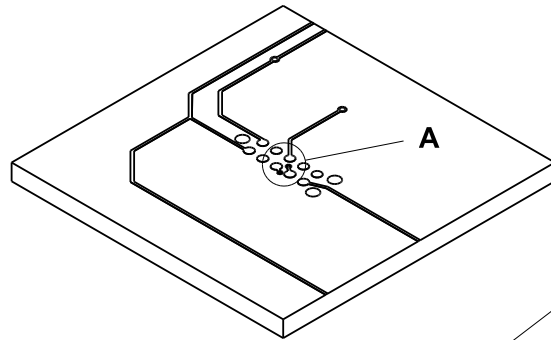
END VIEW
10 PIN TAG-CONNECT



14-pin Ribbon Pin #	TC2050-IDC-430 Pin #
1	1
2	2
...	...
8	8
9	9
10	(NC)
11	10
12	(NC)
13	(NC)
14	(NC)

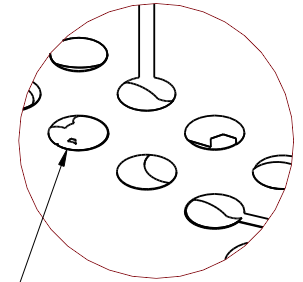
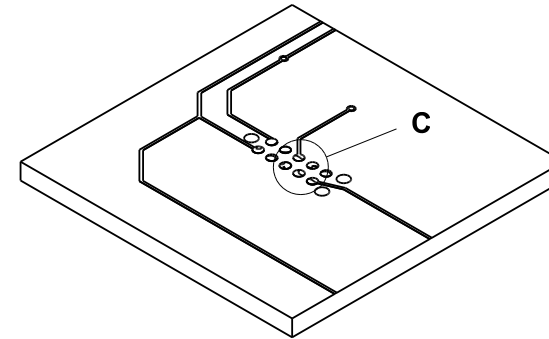
SIZE A	FSCM NO.	DWG NO. TC2050-IDC-430-NL	REV A
SCALE	www.TAG-CONNECT.com SHEET 2 Of 3		

Layout Problems to Avoid



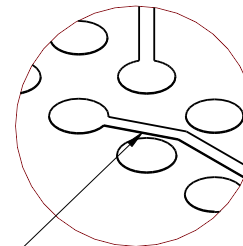
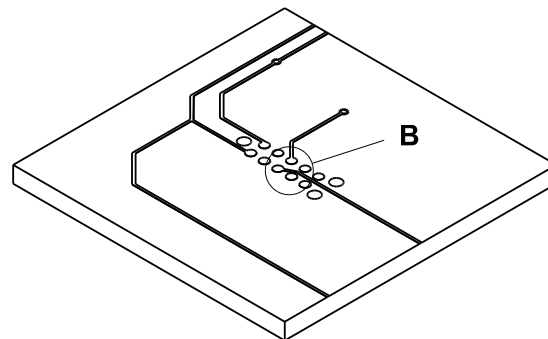
Detail A

Vias between
contact pads



Detail C

Do not deposit solder paste on
contact pads. View Solder Paste
Mask (Solder Stencil) layer in
pad-stack and eliminate any hole.



Detail B

Traces less than .02"
away from contact pad
or in "KEEP OUT" area